

L Number	Hits	Search Text	DB	Time stamp
-	25288	dow.as.	JPO; DERWENT	2002/03/20 19:46
-	3877	globular	JPO; DERWENT	2002/03/20 19:10
-	11	dow.as. and globular	JPO; DERWENT	2002/03/20 19:11
-	1	1996-017489.NRAN.	DERWENT	2002/03/20 19:20
-	0	7292343.URPN.	USPAT	2002/03/20 19:21
-	1	1989-297882.NRAN.	DERWENT	2002/03/20 19:22
-	32	"weight-ppm"	USPAT	2002/03/20 22:16
-	145641	filler	USPAT	2002/03/20 20:35
-	30387	parts adj per adj (million or "1,000,000")	USPAT	2002/03/20 20:06
-	1628	("1,000,000" or million) adj parts adj1 weight!	USPAT	2002/03/20 20:05
-	6211	("1,000,000" or million) near2 parts near2 weight!	USPAT	2002/03/20 20:06
-	12559	ppm near2 weight!	USPAT	2002/03/20 20:07
-	37975	(parts adj per adj (million or "1,000,000")) (("1,000,000" or million) adj parts adj1 weight!) ("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!)	USPAT	2002/03/20 20:07
-	11	filler near2 ((parts adj per adj (million or "1,000,000")) ("1,000,000" or million) adj parts adj1 weight!) ("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!))	USPAT	2002/03/20 20:08
-	34	filler near5 ((parts adj per adj (million or "1,000,000")) ("1,000,000" or million) adj parts adj1 weight!) ("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!))	USPAT	2002/03/20 20:10
-	130331	silicone	USPAT	2002/03/20 20:10
-	144704	epoxy	USPAT	2002/03/20 20:10
-	6	epoxy and (filler near5 ((parts adj per adj (million or "1,000,000")) ("1,000,000" or million) adj parts adj1 weight!) (("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!)))	USPAT	2002/03/20 20:10
-	34118	epoxy and silicone	USPAT	2002/03/20 20:10

-	5	(epoxy and silicone) and (filler near5 ((parts adj per adj (millon or "1,000,000")) ("1,000,000" or million) adj parts adj1 weight!) ("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!)))	USPAT	2002/03/20 20:10
-	1	1996-017489.NRAN.	DERWENT	2002/03/20 20:16
-	1	1996-017489.NRAN.	DERWENT	2002/03/20 20:16
-	0	7292343.URPN.	USPAT	2002/03/20 20:17
-	0	"07292343" "07014859"	USPAT	2002/03/20 20:18
-	0	((("7292343") or ("7014859")),PN.	USPAT	2002/03/20 20:19
-	1	((("7292343") or ("7014859")),PN.	JPO; DERWENT	2002/03/20 20:19
-	4	"07292343" "07014859"	JPO; DERWENT	2002/03/20 20:19
-	24850	standard! adj deviation	USPAT	2002/03/20 20:35
-	0	filler near2 (standard! adj deviation)	USPAT	2002/03/20 20:35
-	18	filler with (standard! adj deviation)	USPAT	2002/03/20 20:36
-	2	silicone and (filler with (standard! adj deviation))	USPAT	2002/03/20 22:17
-	23	silicone and (filler near5 ((parts adj per adj (million or "1,000,000")) ("1,000,000" or million) adj parts adj1 weight!) ("1,000,000" or million) near2 parts near2 weight!) (ppm near2 weight!)))	USPAT	2002/03/20 22:18
-	25	"weight-ppm" and silicone	USPAT	2002/03/20 22:30
-	3854	dow.as.	JPO	2002/03/20 22:30
-	0	dow.as. and "weight-ppm"	JPO	2002/03/20 22:30
-	0	"weight-ppm"	JPO	2002/03/20 22:30
-	219	weight! near4 ppm	JPO	2002/03/20 22:31
-	8	(weight! near4 ppm) and dow.as.	JPO	2002/03/20 22:37
-	8	ppm near5 filler	JPO	2002/03/20 22:41
-	17929	weight! near5 ppm	USPAT	2002/03/20 22:43
-	33	filler near5 (weight! near5 ppm)	USPAT	2002/03/20 22:43
-	15	silicone and (filler near5 (weight! near5 ppm))	USPAT	2002/03/20 22:46

-	1686	underfil\$	USPAT	2002/03/20 22:46
-	314	filler with ppm	USPAT	2002/03/20 22:46
-	4	underfil\$ and (filler with ppm)	USPAT	2002/03/20 22:48
-	118	ppm and underfil\$	USPAT	2002/03/20 22:50
-	287815	adhesive	USPAT	2002/03/21 13:08
-	17091	filler near5 weight	USPAT	2002/03/21 13:09
-	5837	adhesive and (filler near5 weight)	USPAT	2002/03/21 13:10
-	318873	semiconductor integrated adj circuit	USPAT	2002/03/21 13:10
-	503	(adhesive and (filler near5 weight)) and (semiconductor integrated adj circuit)	USPAT	2002/03/21 13:11
-	1354	(filler near5 weight) near5 less	USPAT	2002/03/21 13:11
-	57	((filler near5 weight) near5 less) and adhesive and (semiconductor integrated adj circuit)	USPAT	2002/03/21 13:23
-	207544	surface! adj area	USPAT	2002/03/21 13:24
-	145641	filler	USPAT	2002/03/21 13:24
-	1130	(surface! adj area) near3 filler	USPAT	2002/03/21 13:26
-	31	((surface! adj area) near3 filler) and adhesive and (semiconductor integrated adj circuit)	USPAT	2002/03/21 13:26
-	3	((((surface! adj area) near3 filler) and adhesive and (semiconductor integrated adj circuit)) and (((filler near5 weight) near5 less) and adhesive and (semiconductor integrated adj circuit))	USPAT	2002/03/21 13:27